

This listing of claims replaces all prior versions, and listings, of claims in this application.

Listing of Claims:

1. (Canceled)

2-4 (withdrawn)

5-8 (Canceled)

9. (Withdrawn)

10. (Currently Amended) A mounting structure of a semiconductor device on a circuit substrate, the semiconductor device including: a semiconductor chip; a protective package for covering the semiconductor chip, including at least a pair of opposed side surfaces, each of the side surfaces having a first slanted portion and a second slanted portion each being flat and meeting the other at a predetermined angle; a first lead conducting to the semiconductor chip, including an inner portion covered by the protective package and a plurality of outer portions extending out of the protective package; a second lead conducting to the semiconductor chip, including an inner portion covered by the protective package and a plurality of outer portions extending out of the protective package; the inner portions and the outer portions of the first and the second leads being flat and extending in a same plane; the outer portions of the first lead extending from both of the pair of opposed side surfaces out of the protective package; the outer portions of the second lead extending from both of the opposed side surfaces out of the protective package;

the circuit substrate including: a first surface formed with a predetermined wiring pattern; a second surface opposite to and spaced from the first surface thickness wise of the circuit substrate; a plurality of connecting pads formed in the first surface; and a through hole corresponding to a shape of the protective package;

wherein the protective package is fitted into the through hole of the substrate while partially projecting beyond both of the first and second surfaces of the substrate thickness wise thereof, the outer portions of the first lead and the second lead being connected with the connecting pads.

11. (Original) The mounting structure according to Claim 10, wherein the connecting pads are disposed around the through hole.

12. (Original) The mounting structure according to Claim 10, wherein the first surface mounted with the semiconductor device is laminated with a coating member.

17-18. (Canceled)